



# SOT1899-1

BGA1313, ball grid array package, 1313 terminals, 0.75 mm pitch, 29 mm x 29 mm x 2.37 mm body

28 June 2019

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	BGA1313
<b>Package style descriptive code</b>	BGA (ball grid array)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	04-06-2019
<b>Manufacturer package code</b>	98ASA00969D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	29	-	mm
package width	-	29	-	mm
package height	-	2.37	-	mm
nominal pitch	-	0.75	-	mm
actual quantity of termination	-	1313	-	



2 Package outline

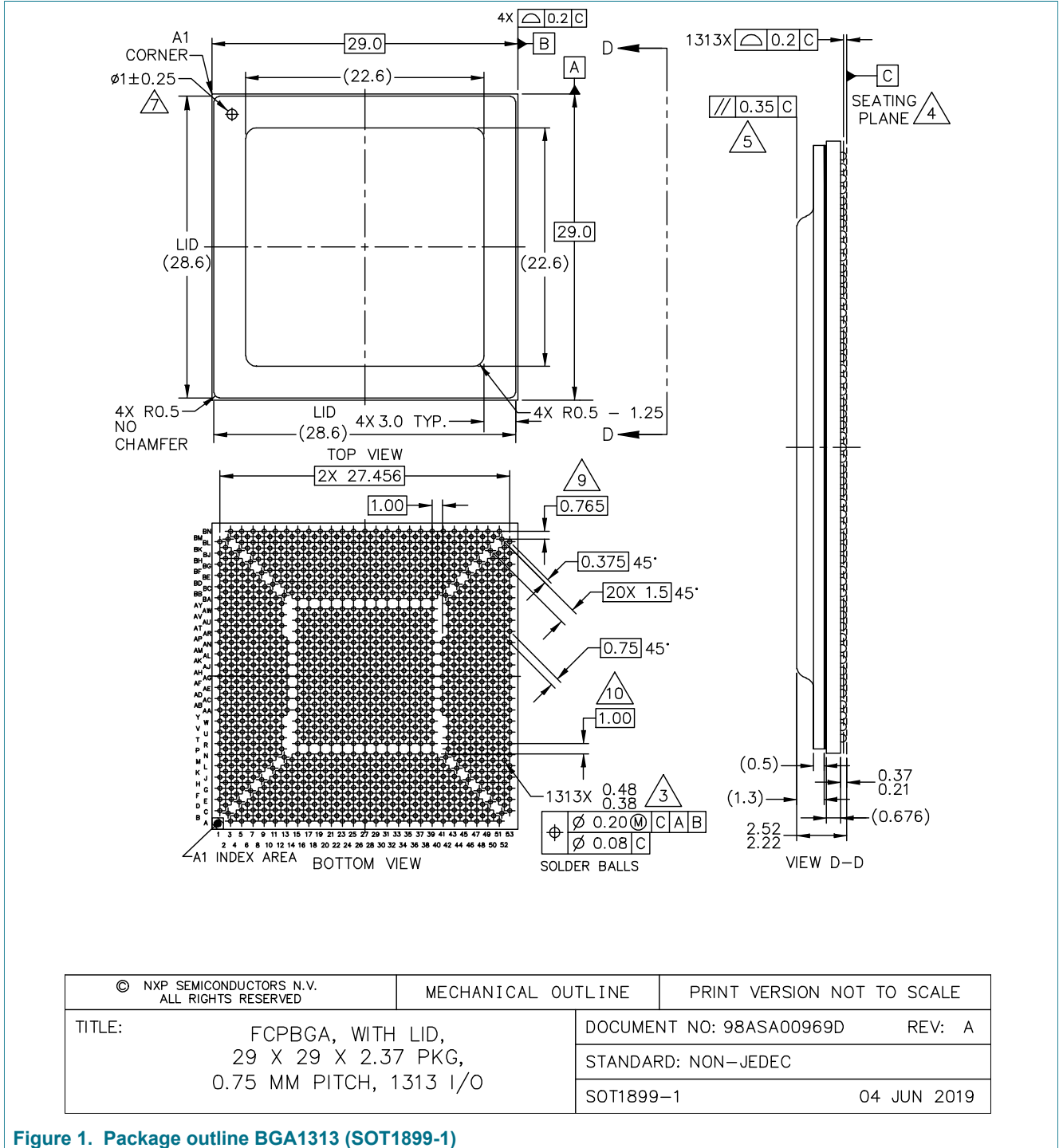


Figure 1. Package outline BGA1313 (SOT1899-1)

BGA1313, ball grid array package, 1313 terminals, 0.75 mm pitch, 29 mm x 29 mm x 2.37 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
4. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
6. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.
7. PIN 1 THRU HOLE SHALL BE CENTERED WITHIN FOOT AREA.
8. LID OVERHANG ON SUBSTRATE NOT ALLOWED.
9. EACH OF THE SIX BALLS IN THE FOUR DIAGONAL LANES BETWEEN DIE CORNER AND PACKAGE CORNER (24 TOTAL BALLS) ARE EQUAL DISTANCE TO THE FOUR CLOSEST SURROUNDING BALLS.
10. 1MM BALL CENTER TO BALL CENTER BETWEEN INNER ARRAY AND OUTER ARRAY FOR ALL FOUR SIDES.

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TITLE: FCPBGA, WITH LID, 29 X 29 X 2.37 PKG, 0.75 MM PITCH, 1313 I/O	DOCUMENT NO: 98ASA00969D	REV: A
	STANDARD: NON-JEDEC	
	SOT1899-1	04 JUN 2019

Figure 2. Package outline note BGA1313 (SOT1899-1)

### 3 Legal information

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Contents

1 Package summary .....1  
2 Package outline .....2  
3 Legal information .....4